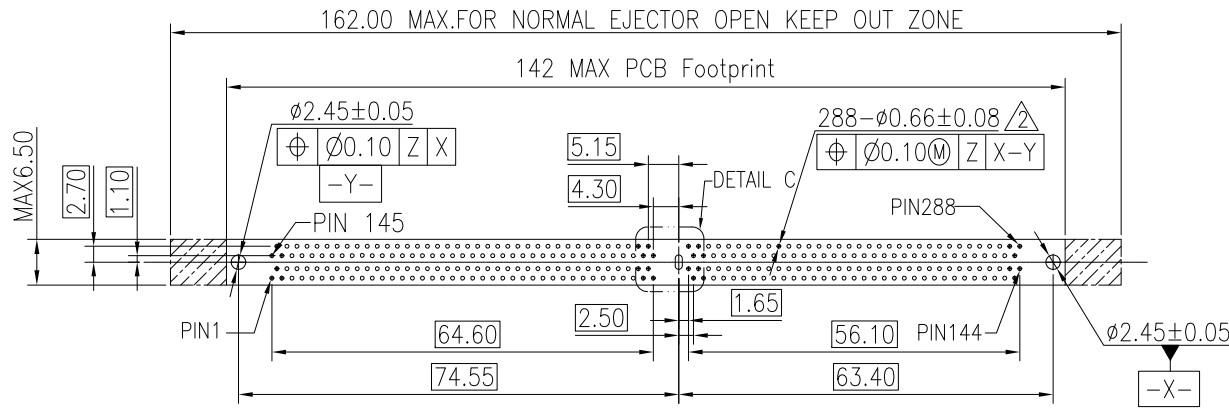


REV.	ECN NO./DESCRIPTION	DATE
L	R140455	08/05'16
M	R180464	01/16'20
N	R180464	05/28'21

GENERAL TOLERANCES UNLESS SPECIFIED		PART NO. <b>SEE TABLE</b>	<b>LOTES</b>		
.X± 0.35	X.°± 3°				
.XX± 0.25	.X.°± 2°	APPROVED BY <b>BIAO.ZHANG 05/28'21</b>	TITLE <b>DDR4 288Pin Conn.</b>		
.XXX± 0.15	.XX.°± 1°	CHECKED BY <b>HONGXING.XU 05/28'21</b>	DWG NO. <b>GAP-ADDR0141</b>		
CUSTOMER DRAWING		DRAWN BY <b>CHEN.XIE 05/28'21</b>	SHEET <b>1 / 4</b>	SCALE <b>4:5</b>	REV <b>N</b>
SIZE <b>A4</b>	UNITS <b>MM[INCH]</b>				

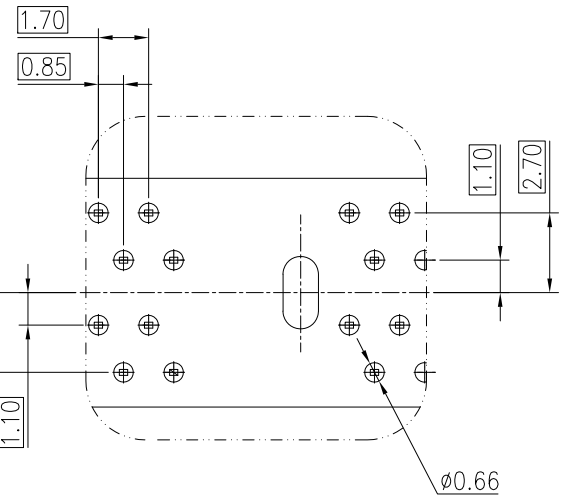
REV.	ECN NO./DESCRIPTION	DATE
L	R140455	08/05'16
M	R180464	01/16'20
N	R180464	05/28'21



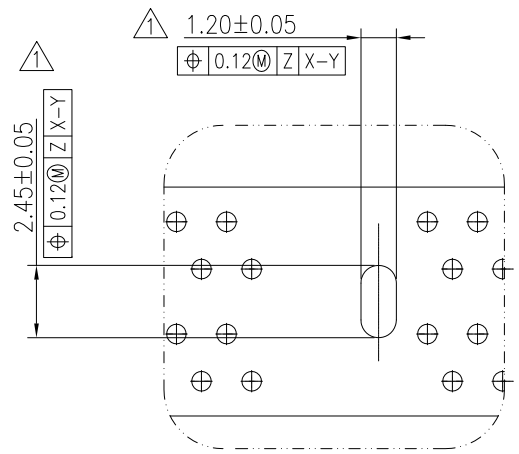
RECOMMENDED PCB LAYOUT(CONNECTOR SIDE) (TOL.:±0.05)



RECOMMENDED PCB LAYOUT&THICKNESS(CONNECTOR SIDE) (TOL.:±0.05)



OUTER LOCUS OF CONNECTOR SOLDER PIN TAILS  
SCALE 5:1

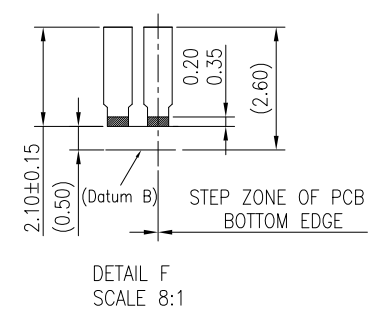
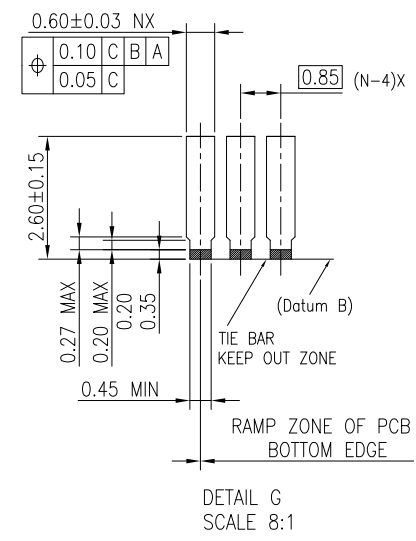
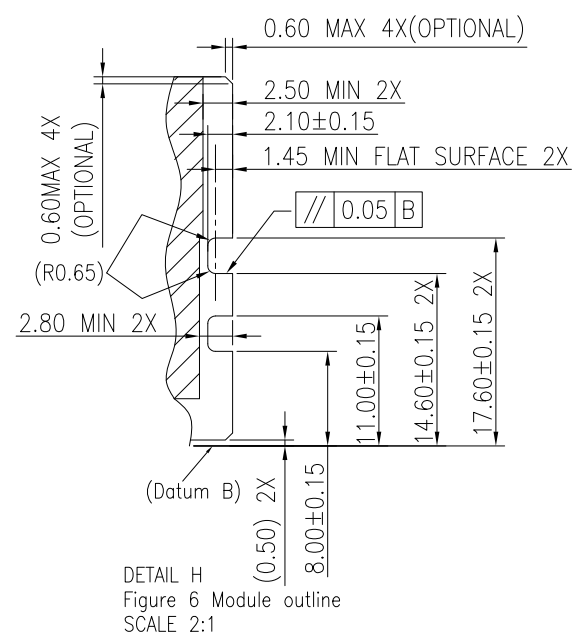
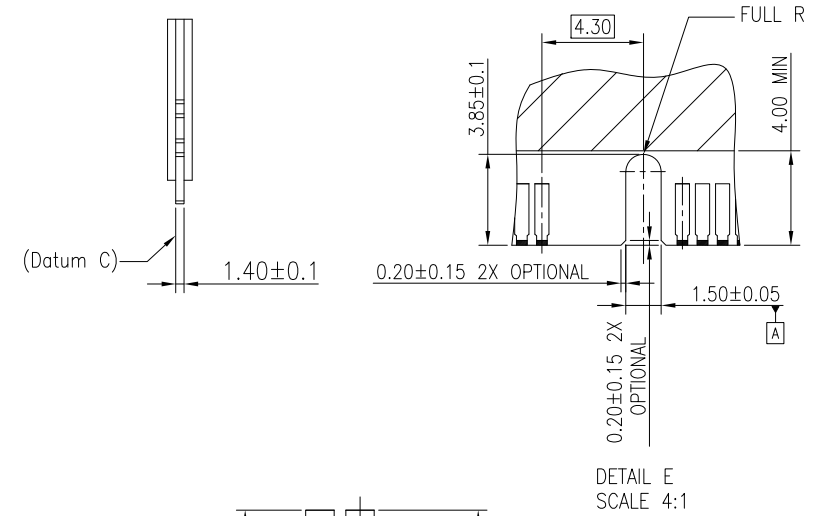
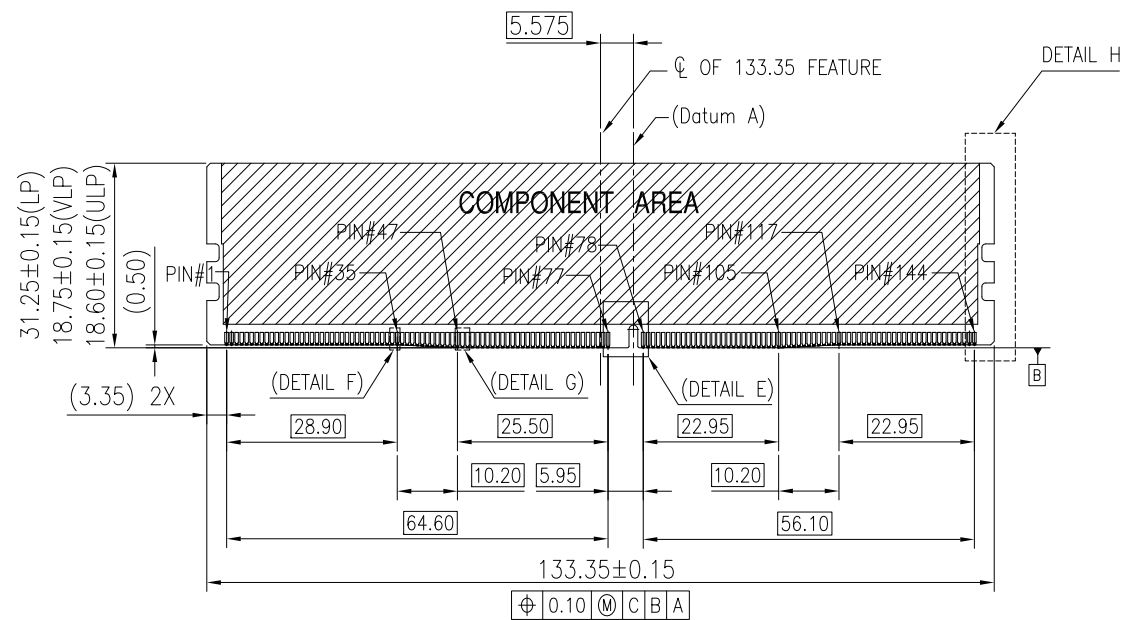


DETAIL C  
SCALE 5:1

① KEEP OUT ZONE IS FOR USABILITY REFERENCE ONLY,ACTUAL DIMM SOCKET DIMENSION WILL FOLLOW DRAWING DEFINITION.  
② RECOMMENDED DIMENSIONS OF THESE FEATURES WERE DERIVED TO ALLOW A ROUTING SOLUTION ON THE MOTHERBOARD.

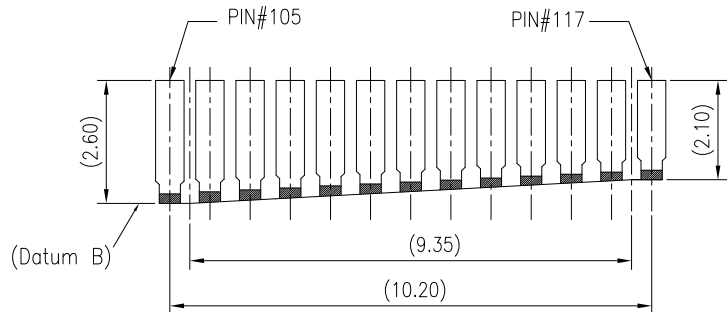
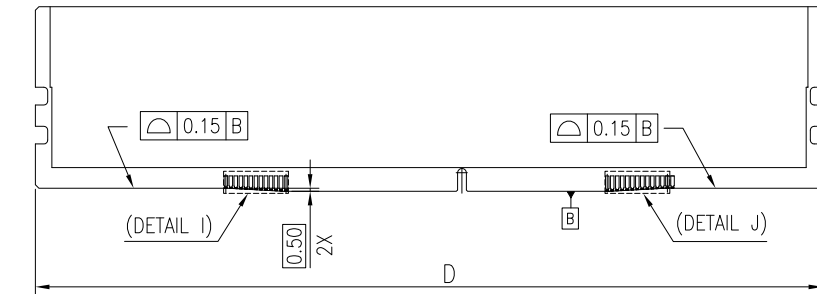
GENERAL TOLERANCES UNLESS SPECIFIED		PART NO.	<b>LOTES</b>		
.X ± 0.35	X.° ± 3°	SEE TABLE	TITLE		
.XX ± 0.25	.X.° ± 2°	APPROVED BY	DDR4 288Pin Conn.		
.XXX ± 0.15	.XX.° ± 1°	BIAO.ZHANG 05/28'21	DWG NO.		
CUSTOMER DRAWING		CHECKED BY	GAP-ADDR0141		
SIZE	UNITS	DRAWN BY	SHEET	SCALE	REV
A4	MM[INCH]	CHEN.XIE 05/28'21			

REV.	ECN NO./DESCRIPTION	DATE
L	R140455	08/05'16
M	R180464	01/16'20
N	R180464	05/28'21



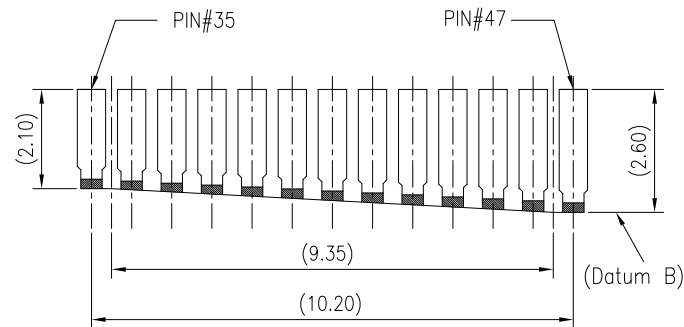
GENERAL TOLERANCES UNLESS SPECIFIED		PART NO.	<b>LOTES</b>		
X± 0.35	X°± 3°	SEE TABLE	TITLE DDR4 288Pin Conn.		
.XX± 0.25	.X°± 2°	APPROVED BY BIAO.ZHANG 05/28'21	DWG NO. GAP-ADDR0141		
.XXX± 0.15	.XX°± 1°	CHECKED BY HONGXING.XU 05/28'21	SHEET 3 / 4		
CUSTOMER DRAWING		DRAWN BY CHEN.XIE 05/28'21	SCALE 4:5		
SIZE A4	UNITS MM[INCH]		REV N		

REV.	ECN NO./DESCRIPTION	DATE
L	R140455	08/05'16
M	R180464	01/16'20
N	R180464	05/28'21



DETAIL J

Figure 7 Step and ramp dimensions



DETAIL I

NOTES:

- MATERIAL: HOUSING: HIGH TEMPERATURE THERMOPLASTIC , UL94V-0, COLOR:SEE TABLE.  
EJECTOR: THERMOPLASTIC UL94V-0, COLOR: SEE TABLE.  
CONTACT: SPECIFIC COPPER OR PHOSPHOR BRONZE.  
HOOK: SUS301.
- FINISH: CONTACT: 50u" OR 90u"MIN NICKEL UNDERPLATED;  
100u"MIN MATTE TIN PLATED ON SOLDER AREA;  
GOLD PLATING AT CONTACT AREA,THICKNESS SEE TABLE.  
HOOK: NO PLATING.
- RECOMMENDED MODULE LAYOUT SHOULD BE M0-XXX FROM JEDEC.
- THE LATCH SHALL BE CLOSED AT ANY TIME ONLY WHEN USED TO INSERT CARD CAN BE OPENED;
- WAVE SODERING TEMPERATURE:  
THE LATCH SHALL BE CLOSED;  
THE CONNECTOR SHALL BE MOUNTED ON THE PCB;  
TEMPERATURE OF THE SOLDER SHALL BE 260±5°C AND IMMERSION DURATION:10±1 SECONDS.
- MECHANICAL PERFORMANCE:  
5-1. INSERTION FORCE-MODULE TO CONNECTOR: 106.8N MAX  
5-2. INSERTION FORCE-CONNECTOR TO BOARD: 75N MAX  
5-3. DURABILITY: 25 CYCLES  
5-4. RETENTION FORCE: 300gf/PIN MIN  
5-5. UNMATING FORCE(PER PIN PAIR): 14gf MIN
- ELECTRICAL PERFORMANCE:  
6-1. VOLTAGE RATING: 1.2V±0.1V  
6-2. CURRENT RATING: 0.75A PER PIN MAX  
6-3. IMPEDANCE: 50ohm  
6-4. LLCR: 10mΩ MAX.(INITIAL), ΔR: 10mΩ MAX  
6-5. INSULATION RESISTANCE: 500V DC, 1MΩ MIN  
6-6. DIELECTRIC WITHSTANDING VOLTAGE: APPLY 500V AC, NO BREAKDOWN.
- ROHS OR HF COMPLIANT.
- D/C \*\* \*\* WEEK  
YEAR
- PRODUCT NUMBER NOTE:

ADDRXXXX-XXXXC

- TRAY PACKING
- PRODUCT SERIES NUMBER
- P:HF COMPLIANT/K:ROHS COMPLIANT
- TYPE SERIES NUMBER
- DDR TYPE
- FINISHED PRODUCT

GENERAL TOLERANCES UNLESS SPECIFIED		PART NO.	<b>LOTES</b>		
X.± 0.35	X°.± 3°	SEE TABLE			
.XX± 0.25	.X°.± 2°	APPROVED BY BIAO.ZHANG 05/28'21			
.XXX± 0.15	.XX°.± 1°	CHECKED BY HONGXING.XU 05/28'21	DWG NO. GAP-ADDR0141		
CUSTOMER DRAWING		DRAWN BY CHEN.XIE 05/28'21			
SIZE A4	UNITS MM[INCH]	DRAWN BY CHEN.XIE 05/28'21	SHEET 4 / 4	SCALE 4:5	REV N

